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STATEMENT BY APPLICANT		Filing Date	November 29, 2005	
		First Named Inventor	Munehiro TADA	
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, , ,		Examiner Name	Not Yet Assigned Bac H. A	
Sheet 1 of 1		Attorney Docket Number	Q91732	

	U.S. PATENT DOCUMENTS							
Examiner Initials*	Cite No.1	Document Number  Kind  Number  Code²  (if known)		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document			
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Examiner Cite	Cite	Foreign Patent Document			Publication Date	Name of Patentee or	Translation <sup>6</sup>
Initials*	No.1	Country Code <sup>3</sup>	Number <sup>4</sup>	101-10-13 104 DD 1000	MM-DD-YYYY	Applicant of Cited Document	Translation
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		NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation
		Tada, M., et al. "BARRIER-METAL-FREE (BMF), Cu DUAL-DAMASCENE INTERCONNECTS WITH	
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		Meeting 2003 Technical Digest, December 8-10, 2003, pages 35.2.1 to 35.2.4.	

Examiner Signature	/Bac Au/	Date Considered	06/07/2008

<sup>\*</sup>EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.